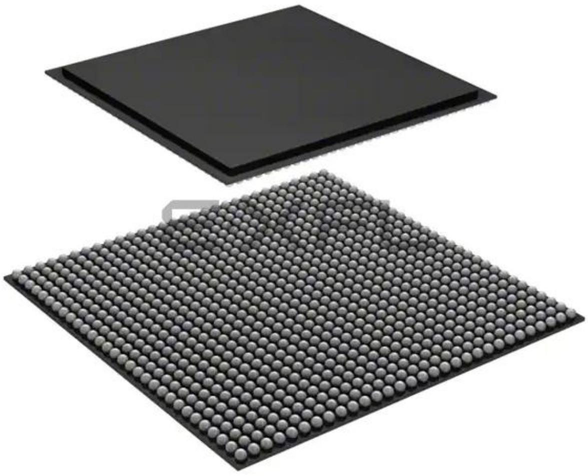
Lattice Semiconductor Corporation - LFE2-70E-5F900I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

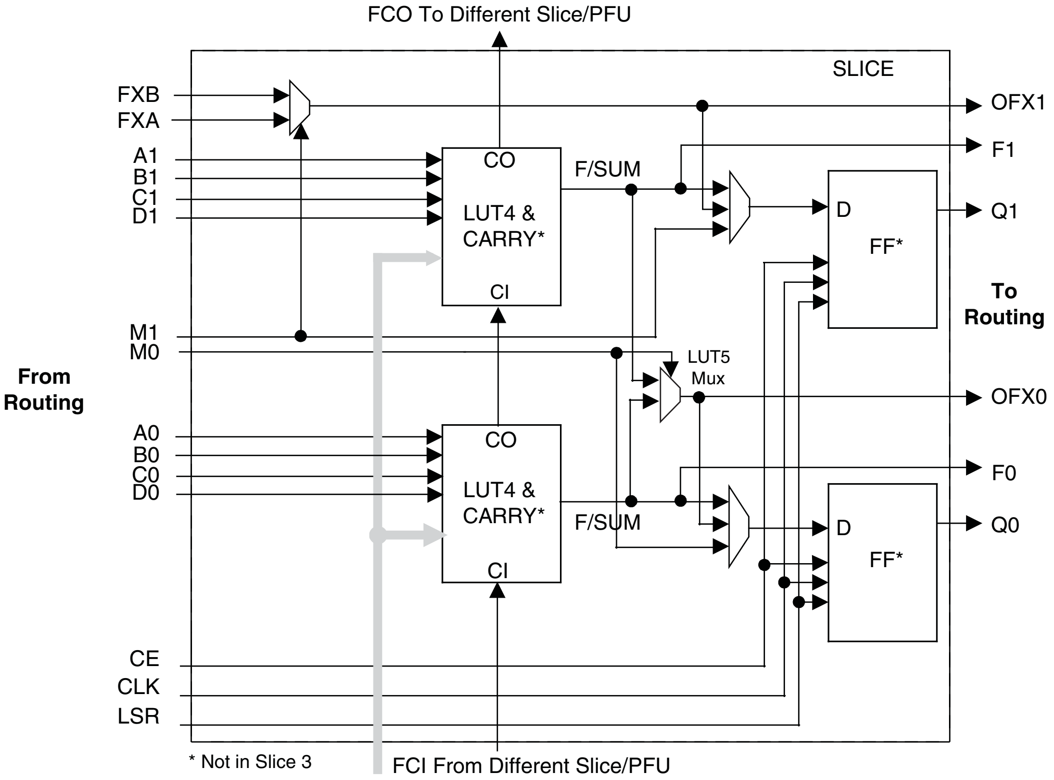
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8500
Number of Logic Elements/Cells	68000
Total RAM Bits	1056768
Number of I/O	583
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-70e-5f900i

Figure 2-4. Slice Diagram



For Slices 0 and 2, memory control signals are generated from Slice 1 as follows:

WCK is CLK
WRE is from LSR
DI[3:2] for Slice 2 and DI[1:0] for Slice 0 data
WAD [A:D] is a 4bit address from slice 1 LUT input

Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FC	Fast Carry-in[1]
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6 and LUT7
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6 and LUT7
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	Slice 2 of each PFU is the fast carry chain output[1]

1. See Figure 2-4 for connection details.
2. Requires two PFUs.

sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

Table 2-12. PIO Signals List

Name	Type	Description
CE0, CE1	Control from the core	Clock enables for input and output block flip-flops
CLK0, CLK1	Control from the core	System clocks for input and output blocks
ECLK1, ECLK2	Control from the core	Fast edge clocks
LSR	Control from the core	Local Set/Reset
GSRN	Control from routing	Global Set/Reset (active low)
INCK[2]	Input to the core	Input to Primary Clock Network or PLL reference inputs
DQS	Input to PIO	DQS signal from logic (routing) to PIO
INDD	Input to the core	Unregistered data input to core
INFF	Input to the core	Registered input on positive edge of the clock (CLK0)
IPOS0, IPOS1	Input to the core	Double data rate registered inputs to the core
QPOS0[1], QPOS1[1]	Input to the core	Gearbox pipelined inputs to the core
QNEG0[1], QNEG1[1]	Input to the core	Gearbox pipelined inputs to the core
OPOS0, ONEG0, OPOS2, ONEG2	Output data from the core	Output signals from the core for SDR and DDR operation
OPOS1 ONEG1	Tristate control from the core	Signals to Tristate Register block for DDR operation
DEL[3:0]	Control from the core	Dynamic input delay control bits
TD	Tristate control from the core	Tristate signal from the core used in SDR operation
DDRCLKPOL	Control from clock polarity bus	Controls the polarity of the clock (CLK0) that feed the DDR input block
DQSXFER	Control from core	Controls signal to the Output block

1. Signals available on left/right/bottom only.
2. Selected I/O.

PIO

The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

Input Register Block

The input register blocks for PIOs in left, right and bottom edges contain delay elements and registers that can be used to condition high-speed interface signals, such as DDR memory interfaces and source synchronous interfaces, before they are passed to the device core. Figure 2-29 shows the diagram of the input register block for left, right and bottom edges. The input register block for the top edge contains one memory element to register the input signal as shown in Figure 2-30. The following description applies to the input register block for PIOs in the left, right and bottom edges of the device.

Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired, the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and, in selected blocks, the input to the DQS delay block. If an input delay is desired, designers can select either a fixed delay or a dynamic delay DEL[3:0]. The delay, if selected, reduces input register hold time requirements when using a global clock.

The input block allows three modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In DDR Mode, two registers are used to sample the data on the positive and negative edges of the DQS signal, creating two data streams, D0 and D1. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2]	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	µA
I_{IH}[1, 3]	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7\ V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7\ V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	µA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	µA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1[4]	I/O Capacitance	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	5	8	pf
C2[4]	Dedicated Input Capacitance	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF}, maximum leakage = 25uA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, f = 1.0MHz.

sysI/O Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3[2]	3.135	3.3	3.465	—	—	—
LVCMOS 2.5[2]	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2[2]	1.14	1.2	1.26	—	—	—
LVTTL[2]	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18[2] Class I, II	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2[2] Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3[2] Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL[2] 15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL[2] 18 Class I, II	1.71	1.8	1.89	0.816	0.9	1.08
LVDS[2]	2.375	2.5	2.625	—	—	—
MLVDS25[1]	2.375	2.5	2.625	—	—	—
LVPECL33[1, 2]	3.135	3.3	3.465	—	—	—
BLVDS25[1, 2]	2.375	2.5	2.625	—	—	—
RSDS[1, 2]	2.375	2.5	2.625	—	—	—
SSTL18D_I[2], II[2]	1.71	1.8	1.89	—	—	—
SSTL25D_ I[2], II[2]	2.375	2.5	2.625	—	—	—
SSTL33D_ I[2], II[2]	3.135	3.3	3.465	—	—	—
HSTL15D_ I[2]	1.425	1.5	1.575	—	—	—
HSTL18D_ I[2], II[2]	1.71	1.8	1.89	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. Input on this standard does not depend on the value of V_{CCIO}.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
[LOC]_SQ_VCCIBm	—	Input buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_VCCOBm	—	Output buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_HDOUTNm	O	High-speed output, negative channel m
[LOC]_SQ_HDOUTPm	O	High-speed output, positive channel m
[LOC]_SQ_HDINNm	I	High-speed input, negative channel m
[LOC]_SQ_HDINPm	I	High-speed input, positive channel m
[LOC]_SQ_VCCTXm[4]	—	Transmitter power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.
[LOC]_SQ_VCCRXm[4]	—	Receiver power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.

1. These signals are relevant for LatticeECP2M family.
2. m defines the associated channel in the Quad.
3. These signals are defined in Quads [LOC] indicates the corner SERDES Quad is located: ULC (upper left), URC (upper right), LLC (lower left), LRC (lower right).
4. When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given. For more information, refer to TN1159, LatticeECP2/M Pin Assignment Recommendations.
5. There may be SPLLs that do not have dedicated I/Os.

LatticeECP2 Pin Information Summary, LFE2-6 and LFE2-12 (Cont.)

Pin Type		LFE2-6		LFE2-12			
		144 TQFP	256 fpBGA	144 TQFP	208 PQFP	256 fpBGA	484 fpBGA
Available DDR-Interfaces per I/O Bank[1]	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	1	0	0	1	1
	Bank3	0	0	0	0	0	0
	Bank4	0	2	0	0	2	3
	Bank5	0	1	0	0	1	3
	Bank6	0	1	0	0	1	1
	Bank7	0	1	0	0	1	1
	Bank8	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	0	0	0	0	0
	Bank3	0	0	0	0	0	0
	Bank4	18	32	18	19	32	46
	Bank5	8	14	10	18	17	46
	Bank6	0	0	0	0	0	0
	Bank7	0	0	0	0	0	0
	Bank8	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
H16	NC	-			NC	-		
H20	NC	-			NC	-		
H18	NC	-			NC	-		
K6	NC	-			NC	-		
J16	NC	-			NC	-		
N18	VCC	-			VCC	-		
N6	VCC	-			VCC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-20E/20SE				LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D4	PT7B	0		C	PT7B	0		C
D3	PT7A	0		T	PT7A	0		T
C2	PT6B	0		C	PT6B	0		C
C1	PT6A	0		T	PT6A	0		T
G8	PT5B	0		C	PT5B	0		C
GND	GNDIO0	-			GNDIO0	-		
G7	PT5A	0		T	PT5A	0		T
E7	PT4B	0		C	PT4B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
F7	PT4A	0		T	PT4A	0		T
E6	PT3B	0		C	PT3B	0		C
E5	PT3A	0		T	PT3A	0		T
G6	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
G5	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T
L12	VCC	-			VCC	-		
L13	VCC	-			VCC	-		
L14	VCC	-			VCC	-		
L15	VCC	-			VCC	-		
M11	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M15	VCC	-			VCC	-		
M16	VCC	-			VCC	-		
N11	VCC	-			VCC	-		
N16	VCC	-			VCC	-		
P11	VCC	-			VCC	-		
P16	VCC	-			VCC	-		
R11	VCC	-			VCC	-		
R12	VCC	-			VCC	-		
R15	VCC	-			VCC	-		
R16	VCC	-			VCC	-		
T12	VCC	-			VCC	-		
T13	VCC	-			VCC	-		
T14	VCC	-			VCC	-		
T15	VCC	-			VCC	-		
D11	VCCIO0	0			VCCIO0	0		
D6	VCCIO0	0			VCCIO0	0		
G9	VCCIO0	0			VCCIO0	0		
K12	VCCIO0	0			VCCIO0	0		
J12	VCCIO0	0			VCCIO0	0		
D16	VCCIO1	1			VCCIO1	1		
D21	VCCIO1	1			VCCIO1	1		
G18	VCCIO1	1			VCCIO1	1		
J15	VCCIO1	1			VCCIO1	1		
K15	VCCIO1	1			VCCIO1	1		
F23	VCCIO2	2			VCCIO2	2		
J20	VCCIO2	2			VCCIO2	2		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-20E/20SE				LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-70E/SE Logic Signal Connections: 900 fpBGA

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
VCCIO	VCCIO7	7		
F4	PL2A	7	VREF2_7	T (LVDS)*
F3	PL2B	7	VREF1_7	C (LVDS)*
H4	PL3A	7		T
G5	PL3B	7		C
GND	GNDIO7	-		
D2	PL4A	7		T (LVDS)*
D1	PL4B	7		C (LVDS)*
E2	PL5A	7		T
VCCIO	VCCIO7	7		
E1	PL5B	7		C
GND	GNDIO7	-		
VCCIO	VCCIO7	7		
F1	PL14A	7	LUM1_SPLLT_IN_A/LDQ12	T (LVDS)*
F2	PL14B	7	LUM1_SPLLC_IN_A/LDQ12	C (LVDS)*
G1	PL15A	7	LUM1_SPLLT_FB_A/LDQ12	T
G2	PL15B	7	LUM1_SPLLC_FB_A/LDQ12	C
GND	GNDIO7	-		
H8	PL18A	7	LDQ21	T
H6	PL18B	7	LDQ21	C
VCCIO	VCCIO7	7		
G4	PL19A	7	LDQ21	T (LVDS)*
G3	PL19B	7	LDQ21	C (LVDS)*
H7	PL20A	7	LDQ21	T
H5	PL20B	7	LDQ21	C
GND	GNDIO7	-		
H2	PL21A	7	LDQS21	T (LVDS)*
H1	PL21B	7	LDQ21	C (LVDS)*
J6	PL22A	7	LDQ21	T
VCCIO	VCCIO7	7		
J8	PL22B	7	LDQ21	C
J2	PL23A	7	LDQ21	T (LVDS)*
J1	PL23B	7	LDQ21	C (LVDS)*
J5	PL24A	7	LDQ21	T
GND	GNDIO7	-		
J7	PL24B	7	LDQ21	C
J4	PL25A	7	LDQ29	T (LVDS)*
J3	PL25B	7	LDQ29	C (LVDS)*
K6	PL26A	7	LDQ29	T
K8	PL26B	7	LDQ29	C
VCCIO	VCCIO7	7		
K2	PL27A	7	LDQ29	T (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
P3	PL54B	7	LDQ54	C (LVDS)*
R6	PL55A	7	LDQ54	T
VCCIO	VCCIO7	7		
R8	PL55B	7	LDQ54	C
P2	PL56A	7	LDQ54	T (LVDS)*
P1	PL56B	7	LDQ54	C (LVDS)*
R5	PL57A	7	PCLKT7_0/LDQ54	T
GND	GNDIO7	-		
R7	PL57B	7	PCLKC7_0/LDQ54	C
R4	PL59A	6	PCLKT6_0/LDQ63	T (LVDS)*
R3	PL59B	6	PCLKC6_0/LDQ63	C (LVDS)*
T5	PL60A	6	VREF2_6/LDQ63	T
T7	PL60B	6	VREF1_6/LDQ63	C
T3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
T4	PL61B	6	LDQ63	C (LVDS)*
T6	PL62A	6	LDQ63	T
T8	PL62B	6	LDQ63	C
T2	PL63A	6	LDQS63	T (LVDS)*
GND	GNDIO6	-		
T1	PL63B	6	LDQ63	C (LVDS)*
U7	PL64A	6	LDQ63	T
U5	PL64B	6	LDQ63	C
VCCIO	VCCIO6	6		
U4	PL65A	6	LDQ63	T (LVDS)*
U3	PL65B	6	LDQ63	C (LVDS)*
U8	PL66A	6	LDQ63	T
U6	PL66B	6	LDQ63	C
GND	GNDIO6	-		
U2	PL67A	6	LDQ71	T (LVDS)*
U1	PL67B	6	LDQ71	C (LVDS)*
V7	PL68A	6	LDQ71	T
V5	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6		
V2	PL69A	6	LDQ71	T (LVDS)*
V1	PL69B	6	LDQ71	C (LVDS)*
V8	PL70A	6	LDQ71	T
V6	PL70B	6	LDQ71	C
GND	GNDIO6	-		
W1	PL71A	6	LDQS71	T (LVDS)*
W2	PL71B	6	LDQ71	C (LVDS)*
W5	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M19	PR50A	3	RDQ52	T (LVDS)*
M18	PR49B	3	RDQ52	C
VCCIO	VCCIO3	3		
L16	PR49A	3	RDQ52	T
L22	PR48B	3	RDQ52	C (LVDS)*
L21	PR48A	3	RDQ52	T (LVDS)*
GNDIO	GNDIO3	-		
K22	PR46B	3	RLM3_SPLLC_FB_A	C
VCCIO	VCCIO3	3		
K21	PR46A	3	RLM3_SPLLT_FB_A	T
L17	PR45B	3	RLM3_SPLLC_IN_A	C (LVDS)*
L18	PR45A	3	RLM3_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO3	-		
L20	PR44B	3		C
L19	PR44A	3		T
K16	PR43B	3		C (LVDS)*
K17	PR43A	3		T (LVDS)*
VCCIO	VCCIO3	3		
J16	PR42B	3	VREF2_3	C
K18	PR42A	3	VREF1_3	T
J22	PR41B	3	PCLKC3_0	C (LVDS)*
J21	PR41A	3	PCLKT3_0	T (LVDS)*
H22	PR39B	2	PCLKC2_0/RDQ36	C
H21	PR39A	2	PCLKT2_0/RDQ36	T
GNDIO	GNDIO2	-		
J17	PR38B	2	RDQ36	C (LVDS)*
J18	PR38A	2	RDQ36	T (LVDS)*
J20	PR37B	2	RDQ36	C
J19	PR37A	2	RDQ36	T
VCCIO	VCCIO2	2		
H16	PR36B	2	RDQ36	C (LVDS)*
H17	PR36A	2	RDQS36	T (LVDS)*
G22	PR35B	2	RDQ36	C
GNDIO	GNDIO2	-		
G21	PR35A	2	RDQ36	T
H20	PR34B	2	RDQ36	C (LVDS)*
H19	PR34A	2	RDQ36	T (LVDS)*
G16	PR33B	2	RUM3_SPLLC_FB_A/RDQ36	C
VCCIO	VCCIO2	2		
H18	PR33A	2	RUM3_SPLLT_FB_A/RDQ36	T
F22	PR32B	2	RUM3_SPLLC_IN_A/RDQ36	C (LVDS)*
F21	PR32A	2	RUM3_SPLLT_IN_A/RDQ36	T (LVDS)*
G20	PR30B	2	RDQ27	C

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
F20	PR30A	2	RDQ27	T
GNDIO	GNDIO2	-		
G17	PR29B	2	RDQ27	C (LVDS)*
F17	PR29A	2	RDQ27	T (LVDS)*
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E22	PR14B	2		C
D22	PR14A	2		T
VCCIO	VCCIO2	-		
E20	PR13B	2		C (LVDS)*
D20	PR13A	2		T (LVDS)*
D19	PR12B	2	RUM0_SPLLC_FB_A	C
GNDIO	GNDIO2	-		
E19	PR12A	2	RUM0_SPLLT_FB_A	T
F18	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*
F19	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*
VCCIO	VCCIO2	-		
E18	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-		
D18	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2		
F16	XRES	-		
C22	URC_SQ_VCCRX0	12		
A21	URC_SQ_HDINP0	12		T
B22	URC_SQ_VCCIB0	12		
B21	URC_SQ_HDINN0	12		C
C19	URC_SQ_VCCTX0	12		
A18	URC_SQ_HDOUTP0	12		T
A19	URC_SQ_VCCOB0	12		
B18	URC_SQ_HDOUTN0	12		C
C18	URC_SQ_VCCTX1	12		
B17	URC_SQ_HDOUTN1	12		C
C17	URC_SQ_VCCOB1	12		
A17	URC_SQ_HDOUTP1	12		T
C21	URC_SQ_VCCRX1	12		
B20	URC_SQ_HDINN1	12		C
C20	URC_SQ_VCCIB1	12		
A20	URC_SQ_HDINP1	12		T
B16	URC_SQ_VCCAUX33	12		
E17	URC_SQ_REFCLKN	12		C
D17	URC_SQ_REFCLKP	12		T
C16	URC_SQ_VCCP	12		
A12	URC_SQ_HDINP2	12		T

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AF4	PB17B	5	BDQ15	C	PB17B	5	BDQ15	C
VCCIO	VCCIO5	5			VCCIO5	5		
AF5	PB18A	5	BDQ15	T	PB18A	5	BDQ15	T
AF6	PB18B	5	BDQ15	C	PB18B	5	BDQ15	C
Y12	PB19A	5	BDQ15	T	PB19A	5	BDQ15	T
GNDIO	GNDIO5	-			GNDIO5	-		
AB11	PB19B	5	BDQ15	C	PB19B	5	BDQ15	C
-	-	-			VCCIO5	5		
-	-	-			GNDIO5	-		
AD7	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
AF7	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
AD8	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AA12	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AE8	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AF8	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
AD9	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
AC10	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
AC11	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AB12	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AD10	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
Y13	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
AF9	PB26A	5	BDQ24	T	PB35A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AE9	PB26B	5	BDQ24	C	PB35B	5	BDQ33	C
AF10	PB27A	5	BDQ24	T	PB36A	5	BDQ33	T
AE10	PB27B	5	BDQ24	C	PB36B	5	BDQ33	C
AD11	PB28A	5	BDQ24	T	PB37A	5	BDQ33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AF11	PB28B	5	BDQ24	C	PB37B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
GNDIO	GNDIO5	-			GNDIO5	-		
AA13	PB33A	5	BDQS33****	T	PB42A	5	BDQS42****	T
AB13	PB33B	5	BDQ33	C	PB42B	5	BDQ42	C
W14	PB34A	5	VREF2_5/BDQ33	T	PB43A	5	VREF2_5/BDQ42	T
AC12	PB34B	5	VREF1_5/BDQ33	C	PB43B	5	VREF1_5/BDQ42	C
AF12	PB35A	5	PCLKT5_0/BDQ33	T	PB44A	5	PCLKT5_0/BDQ42	T
AD12	PB35B	5	PCLKC5_0/BDQ33	C	PB44B	5	PCLKC5_0/BDQ42	C
VCCIO	VCCIO5	5			VCCIO5	5		
GNDIO	GNDIO5	-			GNDIO5	-		
AC13	PB40A	4	PCLKT4_0/BDQ42	T	PB49A	4	PCLKT4_0/BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
Y14	PB40B	4	PCLKC4_0/BDQ42	C	PB49B	4	PCLKC4_0/BDQ51	C
AB20	PB57A	4	BDQ60	T	PB50A	4	VREF2_4/BDQ51	T
AC14	PB41B	4	VREF1_4/BDQ42	C	PB50B	4	VREF1_4/BDQ51	C
AB14	PB42A	4	BDQS42****	T	PB51A	4	BDQS51****	T
GNDIO	GNDIO4	-			GNDIO4	-		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2M35E/SE				LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D23	NC	-			NC	-		
D24	NC	-			NC	-		
D25	NC	-			NC	-		
D26	NC	-			NC	-		
E20	NC	-			NC	-		
E21	NC	-			NC	-		
E25	NC	-			NC	-		
E26	NC	-			NC	-		
F20	NC	-			NC	-		
G20	NC	-			NC	-		
K10	NC	-			NC	-		
K17	NC	-			NC	-		
R4	NC	-			NC	-		
U10	NC	-			NC	-		
U23	NC	-			NC	-		
V10	NC	-			NC	-		
W7	NC	-			NC	-		
AB21	PB69B	4	BDQ69	C	NC	-		
AC20	PB58A	4	BDQ60	T	NC	-		
AC21	PB63A	4	BDQ60	T	NC	-		
AC22	PB69A	4	BDQS69****	T	NC	-		
AC23	PB71A	4	BDQ69	T	NC	-		
AC25	PB71B	4	BDQ69	C	NC	-		
AD26	PB70B	4	BDQ69	C	NC	-		
W20	PB72B	4	BDQ69	C	NC	-		
H7	L_VCCPLL	-			L_VCCPLL	-		
K6	L_VCCPLL	-			L_VCCPLL	-		
P7	L_VCCPLL	-			L_VCCPLL	-		
R8	L_VCCPLL	-			L_VCCPLL	-		
V18	R_VCCPLL	-			R_VCCPLL	-		
P20	R_VCCPLL	-			R_VCCPLL	-		
J17	R_VCCPLL	-			R_VCCPLL	-		
G19	R_VCCPLL	-			R_VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
A21	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A22	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C21	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B19	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B18	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A19	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C18	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
D23	PT73B	1		C	PT82B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
E21	PT73A	1		T	PT82A	1		T
D26	PT72B	1		C	PT81B	1		C
E26	PT72A	1		T	PT81A	1		T
E23	PT71B	1		C	PT80B	1		C
-	-	-			VCCIO1	1		
G22	PT71A	1		T	PT80A	1		T
VCCIO	VCCIO1	1			-	-		
D22	PT70B	1		C	PT79B	1		C
F21	PT70A	1		T	PT79A	1		T
G18	PT69B	1		C	PT78B	1		C
H18	PT69A	1		T	PT78A	1		T
D20	PT68B	1		C	PT77B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
D21	PT68A	1		T	PT77A	1		T
E20	PT67B	1		C	PT76B	1		C
E19	PT67A	1		T	PT76A	1		T
D19	PT66B	1		C	PT75B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
E18	PT66A	1		T	PT75A	1		T
D18	PT65B	1		C	PT74B	1		C
C17	PT65A	1		T	PT74A	1		T
A17	PT64B	1		C	PT73B	1		C
B17	PT64A	1		T	PT73A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO1	1		
J18	NC	-			PT66B	1		C
J19	NC	-			PT66A	1		T
H17	NC	-			PT65B	1		C
J17	NC	-			PT65A	1		T
F18	NC	-			PT64B	1		C
F17	NC	-			PT64A	1		T
-	-	-			GNDIO1	-		
A16	PT54B	1		C	PT63B	1		C
B16	PT54A	1		T	PT63A	1		T
G17	PT53B	1		C	PT62B	1		C
G16	PT53A	1		T	PT62A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
H16	PT52B	1		C	PT61B	1		C
F16	PT52A	1		T	PT61A	1		T

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ30	LRC_SQ_VCCIB0	13		
AK29	LRC_SQ_HDINP0	13		T
AH30	LRC_SQ_VCCRX0	13		
AG27	CFG2	8		
AD25	CFG1	8		
AG28	CFG0	8		
AG30	PROGRAMN	8		
AG29	CCLK	8		
AC24	INITN	8		
AF27	DONE	8		
GNDIO	GNDIO8	-		
AF28	WRITEN***	8		
AE26	CS1N***	8		
AB23	CSN***	8		
AF29	D0/SPIFASTN***	8		
VCCIO	VCCIO8	8		
AF30	D1***	8		
AD26	D2***	8		
AE29	D3***	8		
GNDIO	GNDIO8	-		
AE30	D4***	8		
AD29	D5***	8		
AC25	D6***	8		
AD30	D7/SPID0***	8		
VCCIO	VCCIO8	8		
AA22	DI/CSSPI0N***	8		
AC26	DOUT/CSON/CSSPI1N***	8		
AA23	BUSY/SISPI***	8		
AB22	RLM0_PLLCAP	3		
AC27	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-		
AC28	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AC29	PR101B	3	RLM0_GDLLC_IN_A**/RDQ99	C (LVDS)*
AC30	PR101A	3	RLM0_GDLLT_IN_A**/RDQ99	T (LVDS)*
AB30	PR100B	3	RLM0_GPLLC_IN_A**/RDQ99	C
VCCIO	VCCIO3	3		
AA30	PR100A	3	RLM0_GPLLT_IN_A**/RDQ99	T
AB29	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AB28	PR99A	3	RLM0_GPLLT_FB_A/RDQS99	T (LVDS)*
GNDIO	GNDIO3	-		
Y22	PR98B	3	RDQ99	C
Y23	PR98A	3	RDQ99	T
AB26	PR97B	3	RDQ99	C (LVDS)*

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M10	VCCIO7	7		
M7	VCCIO7	7		
N10	VCCIO7	7		
N3	VCCIO7	7		
P10	VCCIO7	7		
R6	VCCIO7	7		
AA25	VCCIO8	8		
AD28	VCCIO8	8		
AA10	VCCAUX	-		
AA11	VCCAUX	-		
AA20	VCCAUX	-		
AA21	VCCAUX	-		
K10	VCCAUX	-		
K11	VCCAUX	-		
K20	VCCAUX	-		
K21	VCCAUX	-		
L10	VCCAUX	-		
L11	VCCAUX	-		
L20	VCCAUX	-		
L21	VCCAUX	-		
Y10	VCCAUX	-		
Y11	VCCAUX	-		
Y20	VCCAUX	-		
Y21	VCCAUX	-		
A1	GND	-		
A13	GND	-		
A18	GND	-		
A24	GND	-		
A30	GND	-		
A7	GND	-		
AA14	GND	-		
AA15	GND	-		
AA16	GND	-		
AA17	GND	-		
AA24	GND	-		
AA27	GND	-		
AA4	GND	-		
AB24	GND	-		
AB7	GND	-		
AD12	GND	-		
AD19	GND	-		
AD27	GND	-		
AE22	GND	-		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100E-5FN1152C	520	1.2V	-5	Lead-Free fpBGA	1152	COM	100
LFE2M100E-6FN1152C	520	1.2V	-6	Lead-Free fpBGA	1152	COM	100
LFE2M100E-7FN1152C	520	1.2V	-7	Lead-Free fpBGA	1152	COM	100
LFE2M100E-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	COM	100
LFE2M100E-6FN900C	416	1.2V	-6	Lead-Free fpBGA	900	COM	100
LFE2M100E-7FN900C	416	1.2V	-7	Lead-Free fpBGA	900	COM	100

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	IND	20
LFE2M20E-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	IND	20
LFE2M20E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	20
LFE2M20E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	IND	35
LFE2M35E-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	IND	35
LFE2M35E-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	IND	35
LFE2M35E-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	IND	35
LFE2M35E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	35
LFE2M35E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50E-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50E-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50E-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50E-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50E-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70E-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70